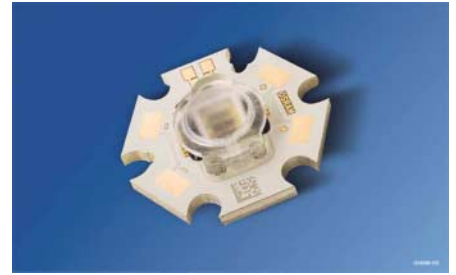


OSTAR® - Lighting IR 6-fold with Optics (850nm) Lead (Pb) Free Product - RoHS Compliant

SFH 4750



Vorläufige Daten / Preliminary Data

Wesentliche Merkmale

- 3.5 W optische Leistung bei IF=1A
- Aktive Chipfläche 2.1 x 3.2 mm²
- max. Gleichstrom 1 A
- niedriger Wärmewiderstand (3 K/W)
- Emissionswellenlänge 850 nm
- ESD-sicher bis 2 kV nach JESD22-A114-B

Anwendungen

- Infrarotbeleuchtung für CMOS Kameras
- Überwachungssysteme
- IR-Datenübertragung
- Verkehrsüberwachungssysteme
- Beleuchtung für Bilderkennungssysteme

Sicherheitshinweise

Je nach Betriebsart emittieren diese Bauteile hochkonzentrierte, nicht sichtbare Infrarot-Strahlung, die gefährlich für das menschliche Auge sein kann. Produkte, die diese Bauteile enthalten, müssen gemäß den Sicherheitsrichtlinien der IEC-Normen 60825-1 und 62471 behandelt werden.

Features

- 3.5 W optical power at IF=1A
- Active chip area 2.1 x 3.2 mm²
- max. DC-current 1 A
- Low thermal resistance (3 K/W)
- Spectral emission at 850 nm
- ESD save up to 2 kV acc. to JESD22-A114-B

Applications

- Infrared Illumination for CMOS cameras
- Surveillance systems
- IR Data Transmission
- Intelligent Transportation Systems
- Machine vision systems

Safety Advices

Depending on the mode of operation, these devices emit highly concentrated non visible infrared light which can be hazardous to the human eye. Products which incorporate these devices have to follow the safety precautions given in IEC 60825-1 and IEC 62471.

Typ Type	Bestellnummer Ordering Code	Strahlstärke ¹⁾ ($I_F = 1A, t_p = 20 ms$) Radiant intensity ¹⁾ I_e (mW/sr)
SFH 4750	Q65110A8280	> 630 (typ. 1000)

¹⁾ gemessen bei einem Raumwinkel $\Omega = 0.01$ sr / measured at a solid angle of $\Omega = 0.01$ sr.

Grenzwerte $T_B^{1)} = 25\text{ °C}$ **Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{B, op}, T_{B, stg}$	- 40 ... + 100	°C
Sperrschichttemperatur Junction temperature	T_J	+ 145	°C
Sperrspannung Reverse voltage	V_R	0.5	V
Vorwärtsgleichstrom Forward current	I_F	1	A
Stoßstrom, $t_p = 100\ \mu\text{s}$, $D = 0$ Surge current	I_{FSM}	5	A
Leistungsaufnahme, Power consumption	P_{tot}	12	W
Thermische Verlustleistung Thermal power-dissipation	P_{th}	9.8	W
Wärmewiderstand Sperrschicht / Bodenplatte Thermal resistance Junction / Base plate	R_{thJB}	3	K/W

¹⁾ T_B = Temperatur auf der Rückseite der Metallkernplatte / Temperature at the backside of the base plate.

Kennwerte ($T_B = 25\text{ °C}$)**Characteristics**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Wellenlänge der Strahlung Wavelength at peak emission $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	λ_{peak}	860	nm
Schwerpunkts-Wellenlänge der Strahlung Centroid wavelength $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	$\lambda_{centroid}$	850	nm
Spektrale Bandbreite bei 50% von I_{max} Spectral bandwidth at 50% of I_{max} $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	$\Delta\lambda$	30	nm
Abstrahlwinkel Half angle	φ	± 70	Grad deg.

Kennwerte ($T_B = 25\text{ °C}$)

Characteristics (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Abmessungen der aktiven Chipfläche ¹⁾ Dimension of the active chip area	$L \times B$ $L \times W$	2.1 × 3.2	mm ²
Schaltzeiten, I_e von 10% auf 90% und von 90% auf 10%, $I_F = 1\text{ A}$, $R_L = 50\ \Omega$ Switching times, I_e from 10% to 90% and from 90% to 10%, $I_F = 1\text{ A}$, $R_L = 50\ \Omega$	t_r , t_f	10, 10	ns
Durchlassspannung Forward voltage $I_F = 1\text{ A}$, $t_p = 100\ \mu\text{s}$	V_F	9.5 (< 12)	V
Gesamtstrahlungsfluss Total radiant flux $I_F = 1\text{ A}$, $t_p = 100\ \mu\text{s}$	$\Phi_{e\text{ typ}}$	3.5	W
Temperaturkoeffizient von I_e bzw. Φ_e Temperature coefficient of I_e or Φ_e $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	TC_I	- 0.3	%/K
Temperaturkoeffizient von V_F Temperature coefficient of V_F $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	TC_V	- 6	mV/K
Temperaturkoeffizient von λ Temperature coefficient of λ $I_F = 1\text{ A}$, $t_p = 10\text{ ms}$	$TC_{\lambda, \text{centroid}}$	+ 0.3	nm/K

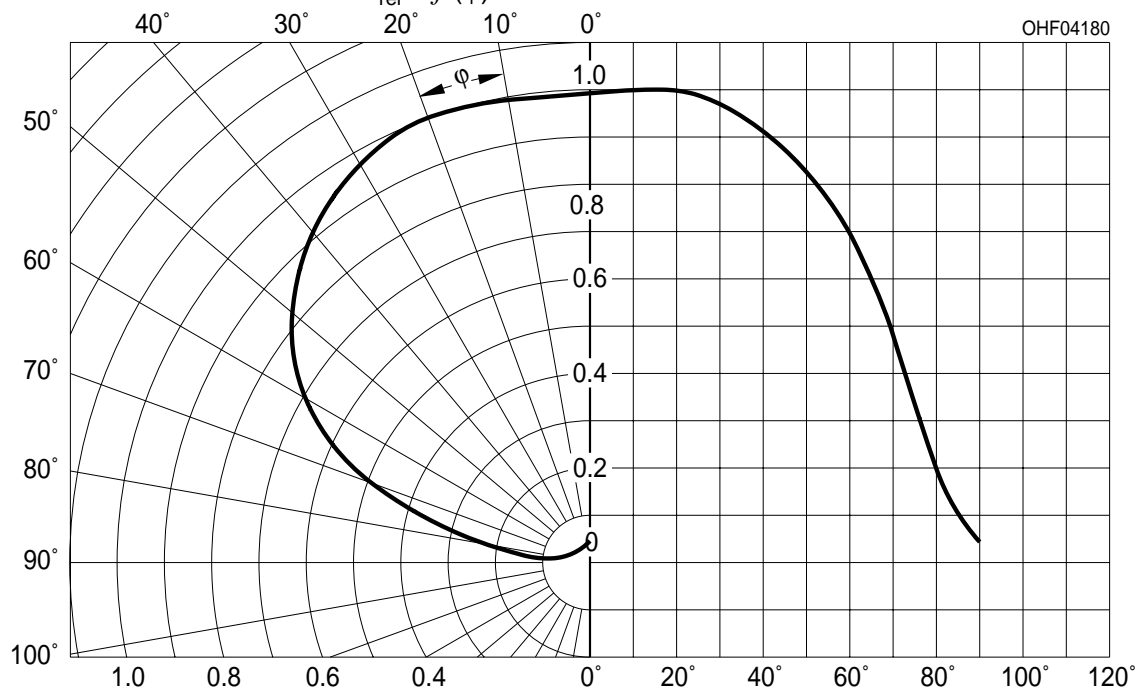
¹⁾ Die aktive Chipfläche besteht aus 6 einzelnen Chips mit je 1 x 1 mm².
The active chip area consists of 6 single chips with 1 x 1 mm² each.

Strahlstärke¹⁾ I_e
 Radiant Intensity¹⁾ I_e

Bezeichnung Parameter	Symbol	Werte Values			Einheit Unit
		SFH 4750 -EA	SFH 4750 -EB	SFH 4750 -FA	
Strahlstärke Radiant Intensity $I_F = 1 \text{ A}, t_p = 20 \text{ ms}$	$I_{e \text{ min}}$ $I_{e \text{ max}}$	630 1000	800 1250	1000 1600	mW/sr mW/sr

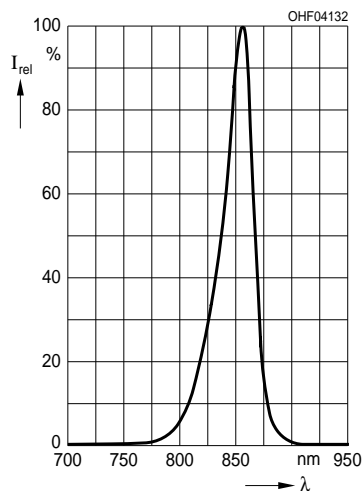
¹⁾ Nur eine Gruppe in einer Verpackungseinheit (Streuung kleiner 1.6:1)
 Only one group in one packing unit (variation lower 1.6:1)

Abstrahlcharakteristik
 Radiation Characteristics $I_{rel} = f(\varphi)$



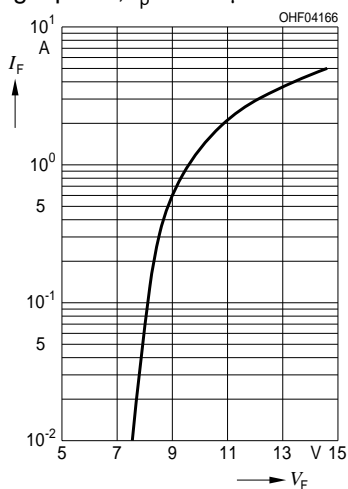
Relative spektrale Emission
Relative Spectral Emission

$I_{rel} = f(\lambda), T_B = 25\text{ °C}$



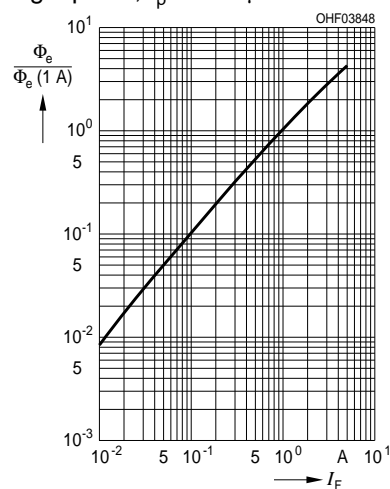
Durchlassstrom
Forward Current

$I_F = f(V_F), T_B = 25\text{ °C},$
Single pulse, $t_p = 100\text{ }\mu\text{s}$



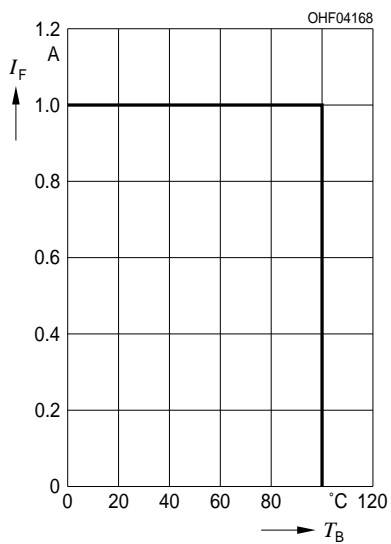
Relativer Gesamtstrahlungsfluss
Relative Total Radiant Flux

$\Phi_e / \Phi_e(1A) = f(I_F), T_B = 25\text{ °C},$
Single pulse, $t_p = 100\text{ }\mu\text{s}$



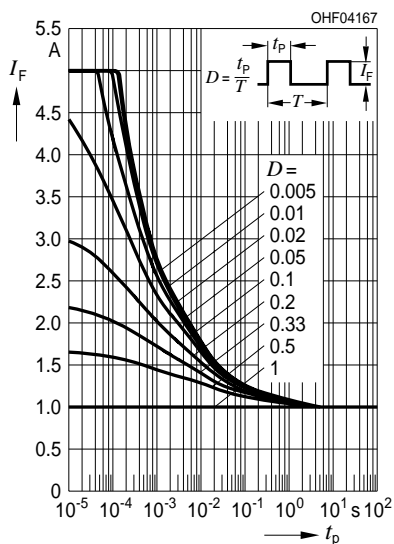
Max. zulässiger Durchlassstrom
Max. Permissible Forward Current

$I_F = f(T_B), R_{thJB} = 3\text{ K/W}$



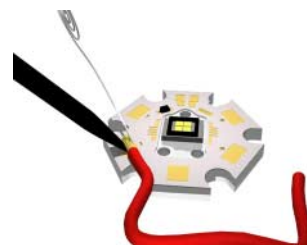
Zulässige Impulsbelastbarkeit
Permissible Pulse Handling

Capability $I_F = f(t_p), T_B = 85\text{ °C},$
Duty cycle $D = \text{parameter}$

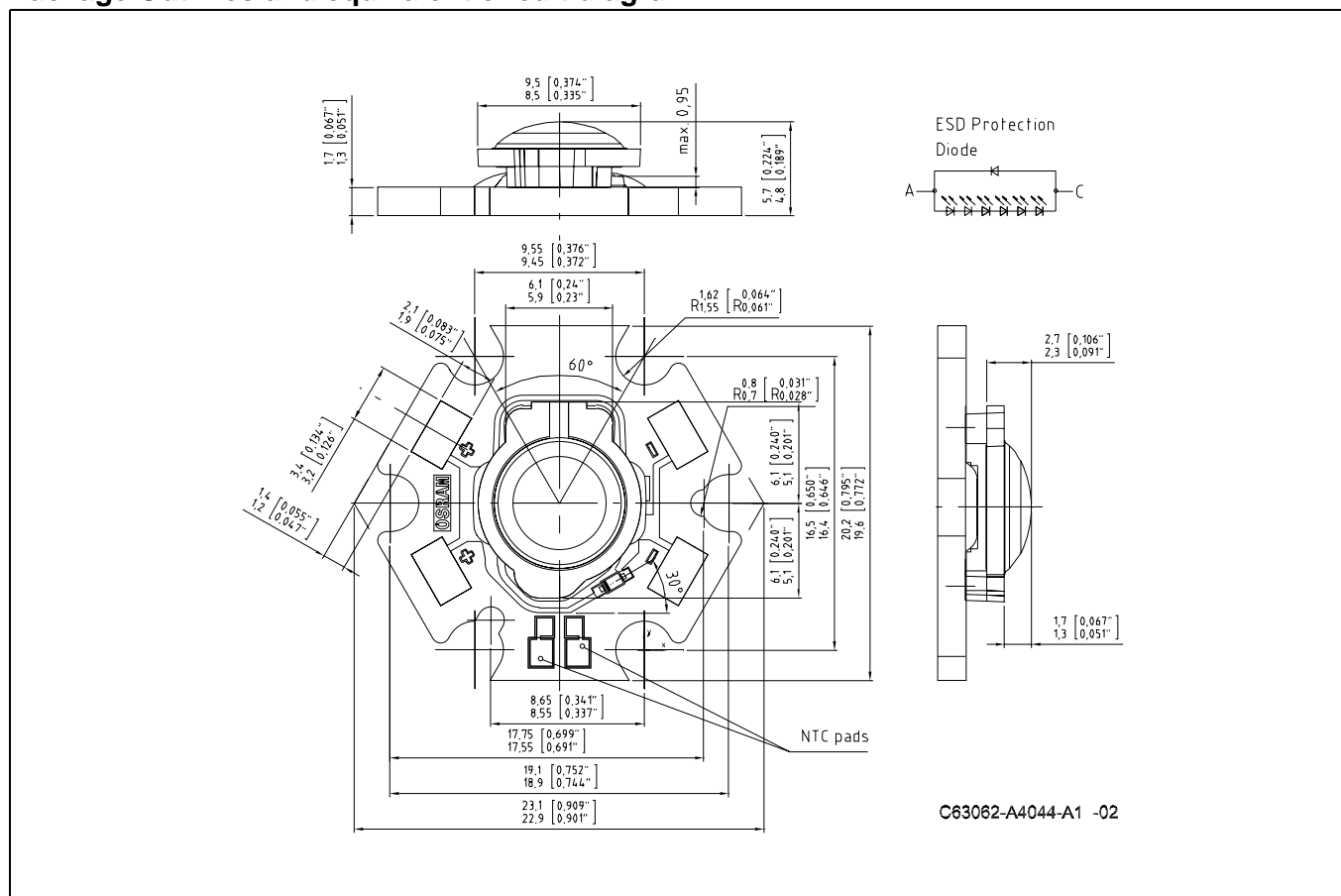


Anschlusskontaktierung
Contacting

Drahttyp Wire type	Durchmesser Diameter	Lötspitze Solder Tip	Temperatur Temperature	Lötzeit Solder Time
AWG 18	~0.8 mm (Litze; flexible wire)	3.2 mm (Meisel; Chisel)	250 °C 350 °C	16 sec. 6 sec
AWG 20	~0.5 mm (Litze; flexible wire)	3.2 mm (Meisel; Chisel)	250 °C 350 °C	14 sec. 5 sec
AWG 22	~0.3 mm (Litze; flexible wire)	3.2 mm (Meisel; Chisel)	250 °C 350 °C	9 sec. 3 sec



Maßzeichnung und Ersatzschaltbild Package Outlines and equivalent circuit diagram



Maße in mm (inch) / Dimensions in mm (inch).

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Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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